


 WN-2631
 2002-318271

UNITED STATES

DECLARATION FOR PATENT APPLICATION

Docket No. _____

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

MEMORY MODULE, MEMORY CHIP, AND MEMORY SYSTEM

the specification of which

(check one) ☐ is attached hereto
☒ was filed on 10/31/2003 as
 Application Serial No. 10/699,628
 and was amended on _____ (if applicable)

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by an amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations § 1.56(a).

I hereby claim foreign priority benefit under Title 35, United States Code, §119 of any foreign application (s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application (s)

			Priority Claimed	
			yes	no
<u>318271/2002</u> (Number)	<u>Japan</u> (Country)	<u>31/10/2002</u> (Day/Month/Year Filed)	yes	xxx
_____ (Number)	_____ (Country)	_____ (Day/Month/Year Filed)	yes	no
_____ (Number)	_____ (Country)	_____ (Day/Month/Year Filed)	yes	no

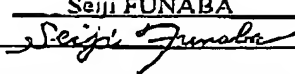

I hereby declare the benefit under title 35, United States Code §120 of any United States application (s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of title 35, United States Code, §112, I acknowledge the duty to disclose material information as defined in title 37, Code of Federal regulations §1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

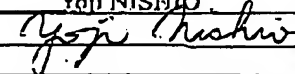

(Application Serial No.)	(Filing Date)	(States-patented, pending, abandoned)
_____ (Application Serial No.)	_____ (Filing Date)	_____ (States-patented, pending, abandoned)

I hereby appoint as my attorney and agent Aaron B. Karas, Reg. No. 18,923, Samson Helfgott, Reg. No. 23,072, Linda S. Chan, Reg. No. 42,400, Michael Markowitz, Reg. No. 30,659, Brian Myers, Reg. No. 46,947, Harris Wolin, Reg. No. 39,432, Shahann Islam, Reg. No. 32,507, Emma Shleifer, Reg. No. 29,734, Serle Mosoff, Reg. No. 25,900, and Thomas J. Bean, Reg. No. 44,528 to prosecute this application and to transmit all business in the Patent and Trademark Office connected therewith.

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Inventor's signature _____ Date _____
Residence _____ Citizenship _____
Post Office Address _____

Full name of fourth inventor _____
Inventor's signature _____ Date _____
Residence _____ Citizenship _____
Post Office Address _____

Full name of fifth inventor _____
Inventor's signature _____ Date _____
Residence _____ Citizenship _____
Post Office Address _____

Full name of sixth inventor _____
Inventor's signature _____ Date _____
Residence _____ Citizenship _____
Post Office Address _____